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EVP, AMD & President and CEO,
Spancion LLC

November 12, 2004

Spancion LLC - The New Industry Leader

60% AMD : 40% Fujitsu



SUNNYVALE, CA

World Headquarters & SDC (45, 65, 90nm)
• 800 employees



AIZU-WAKAMATSU, JAPAN

JV1, JV2, JV3, SP1 Fabs
(45, 65, 90, 110, 130, 230nm)
• 1,600 employees

SUZHOU, CHINA

Final Manufacturing
• 900 employees



TOKYO, JAPAN

Japan Headquarters
• 250 employees

AUSTIN, TX

Fab 25 (65, 90, 110, 130nm)
• 1,200 employees



Production
Actual
2005
Future

PENANG, MALAYSIA

Final Manufacturing
• 500 employees



KUALA LUMPUR, MALAYSIA

Final Manufacturing
• 800 employees

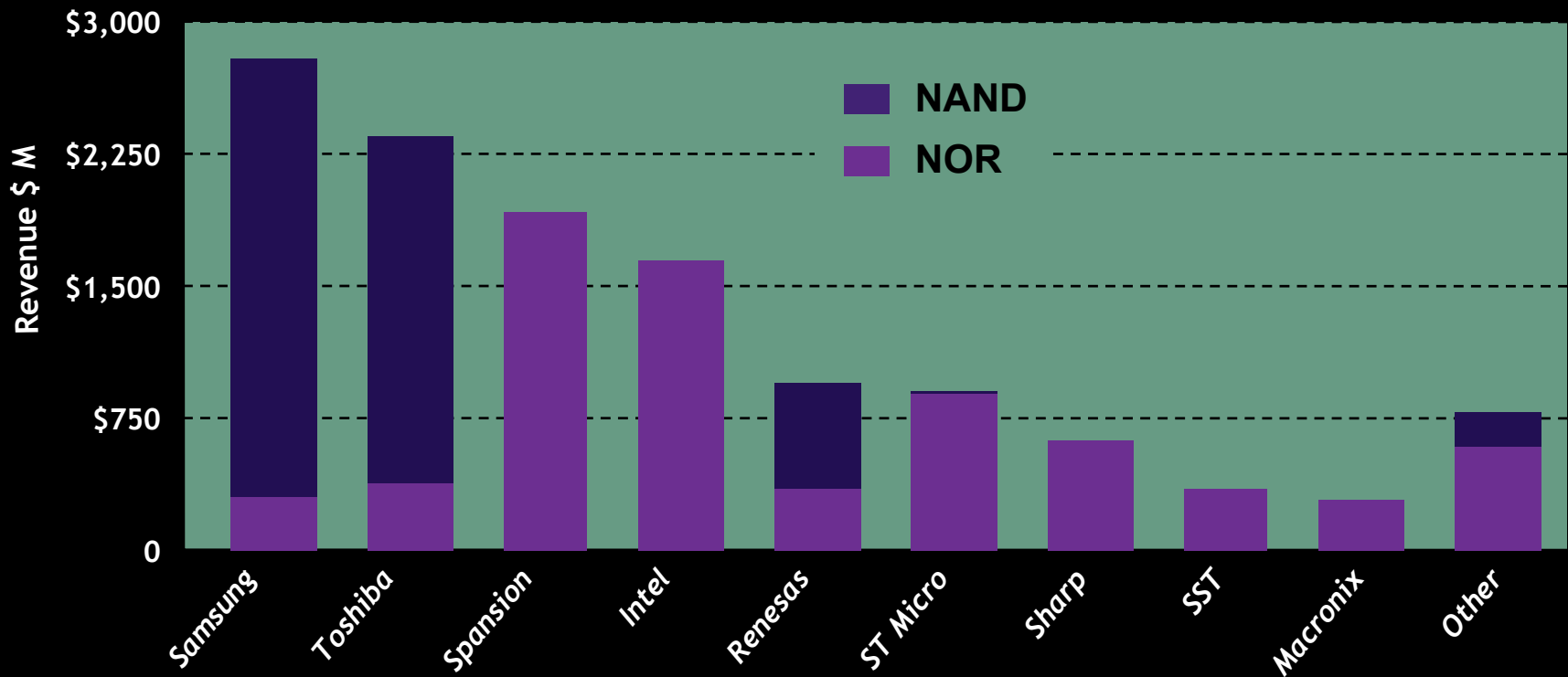
BANGKOK, THAILAND

Final Manufacturing
• 1,300 employees

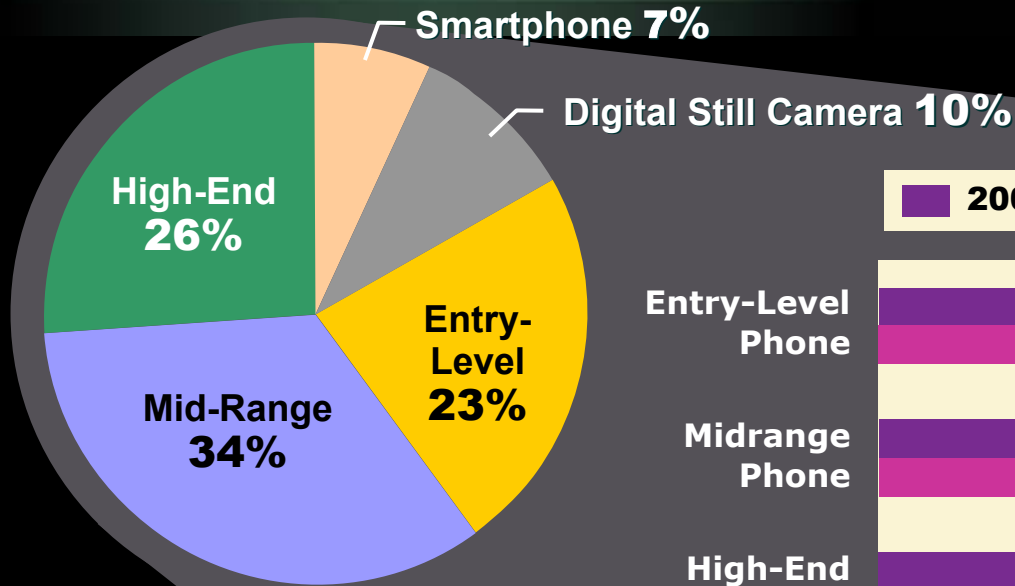
First 3 Quarters of 2004: Competitive Landscape



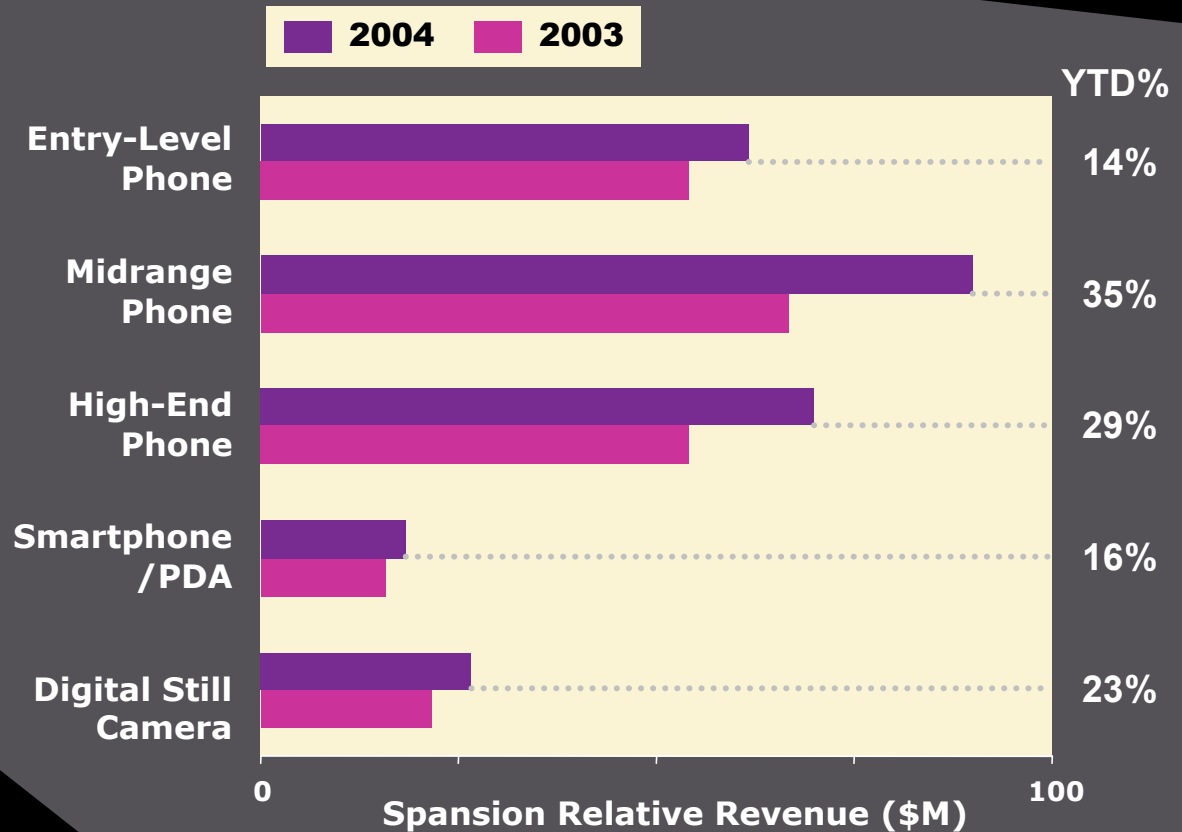
Spansion #1 Overall in NOR Flash Memory



Wireless Market Share Gain (\$): 24% → 26%



**2004
Spancion Focus
by Segment**



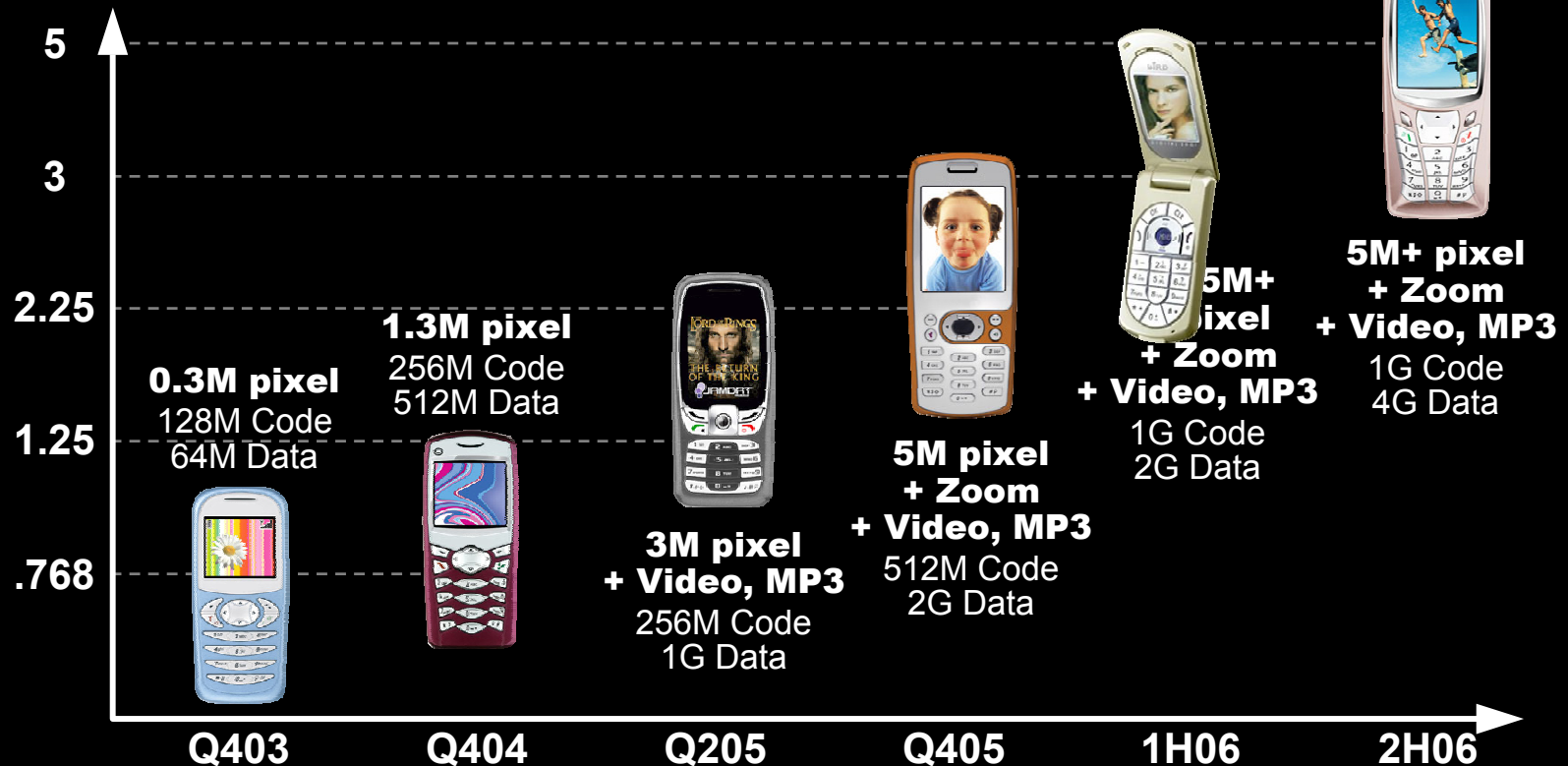
Source: Spancion estimates

High-End Mobile Phone Trends

Handsets Integrate Mobile Digital Functions

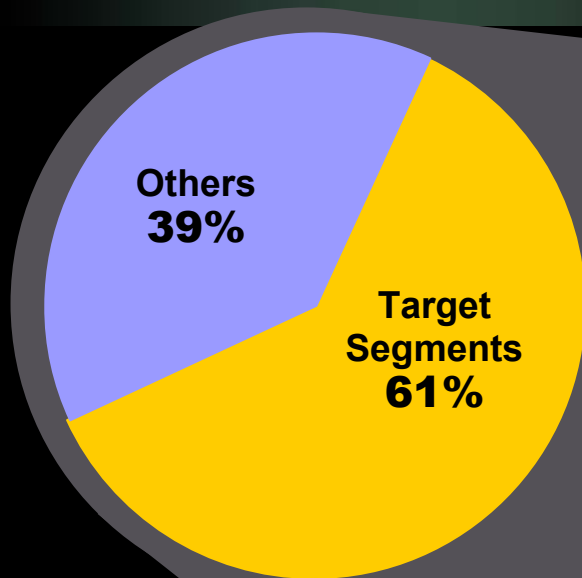


Flash Density (Gbits)



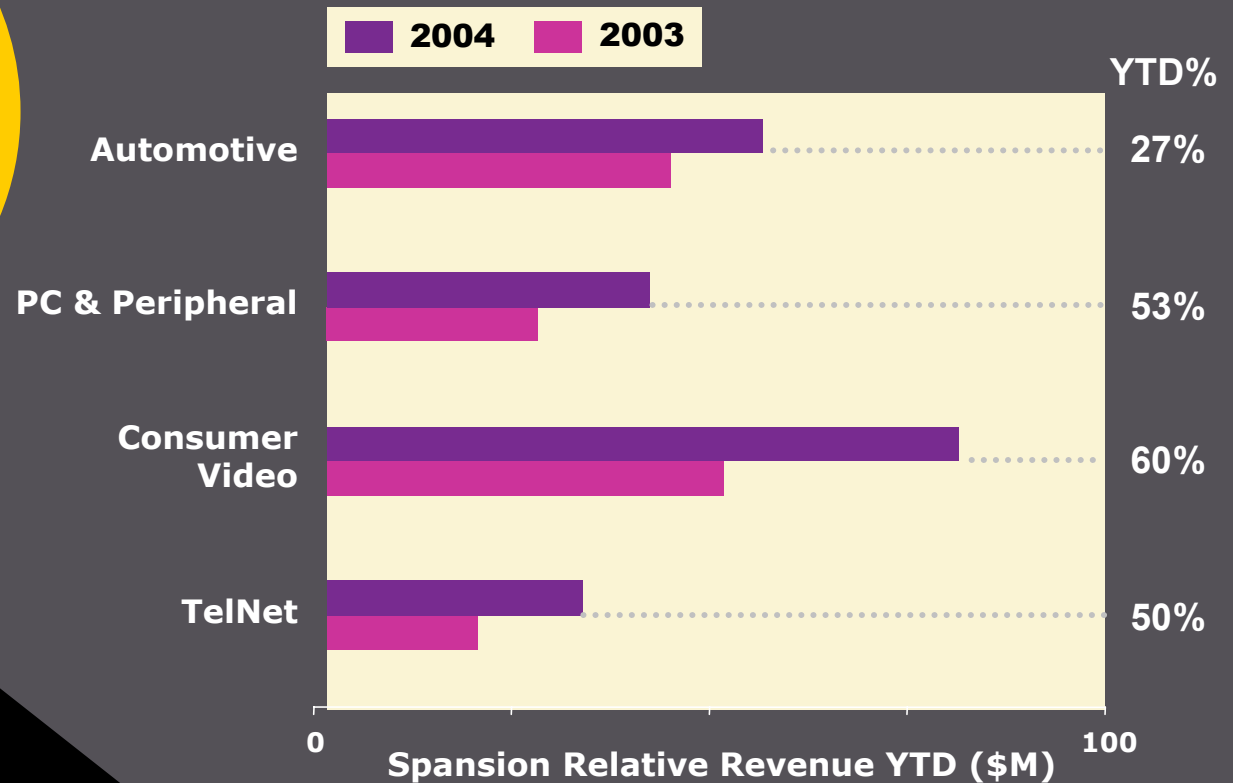
Mbits Per Avg. Phone:	100 Mb	180 Mb	230 Mb	310 Mb	415 Mb	560 Mb
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Embedded Market Share Gain (\$):
24% → 26%



**2004
Spansion Focus
by Segment**

Top 50 Embedded Customers



Source: Spansion estimates

**MEMORY
SUPPLIER**

***Valued
Memory Partner***

Customer Engagement

System Level Innovation

Chip Level Innovation

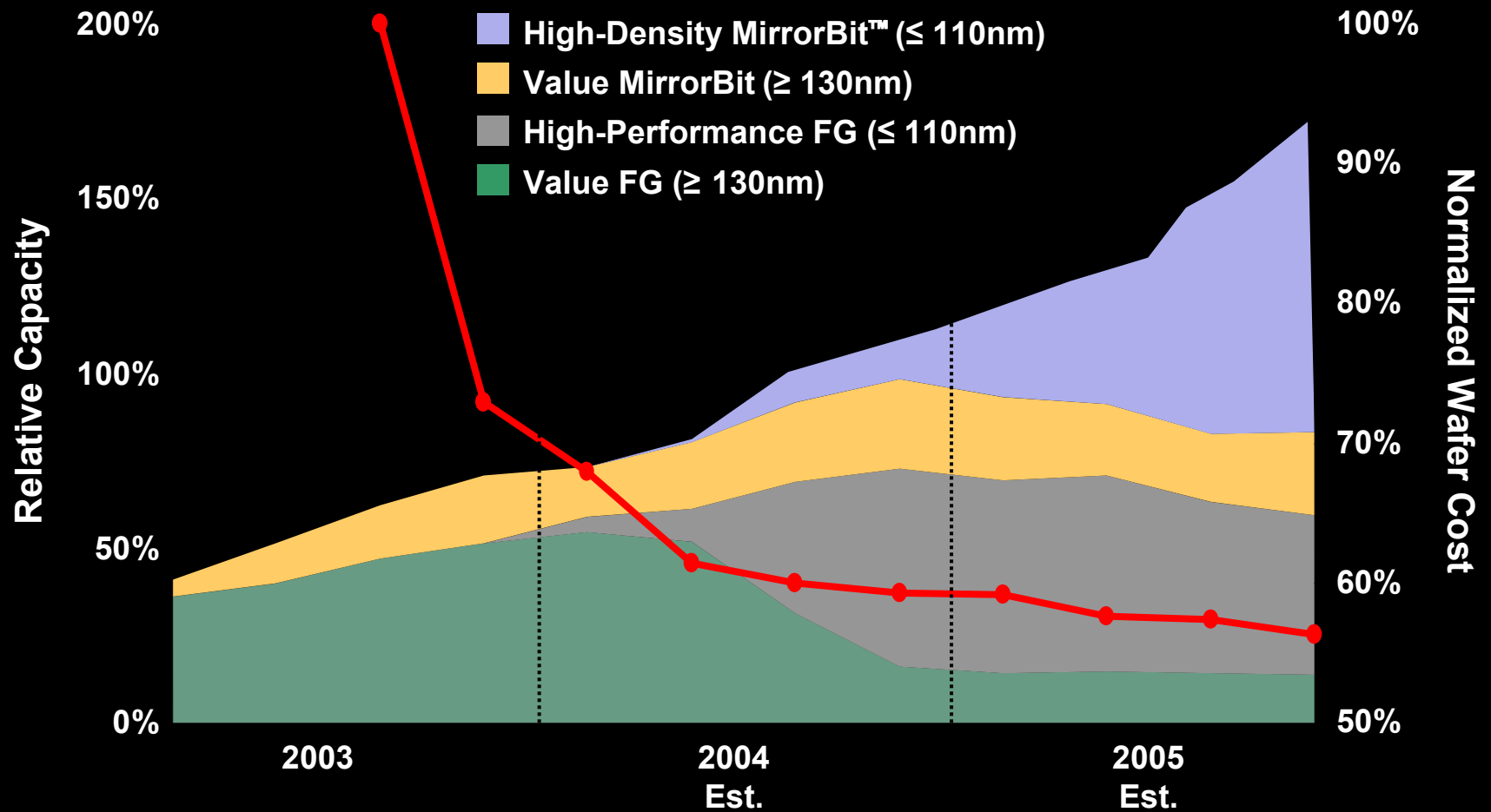
Innovative Flash Technology

Manufacturing Excellence

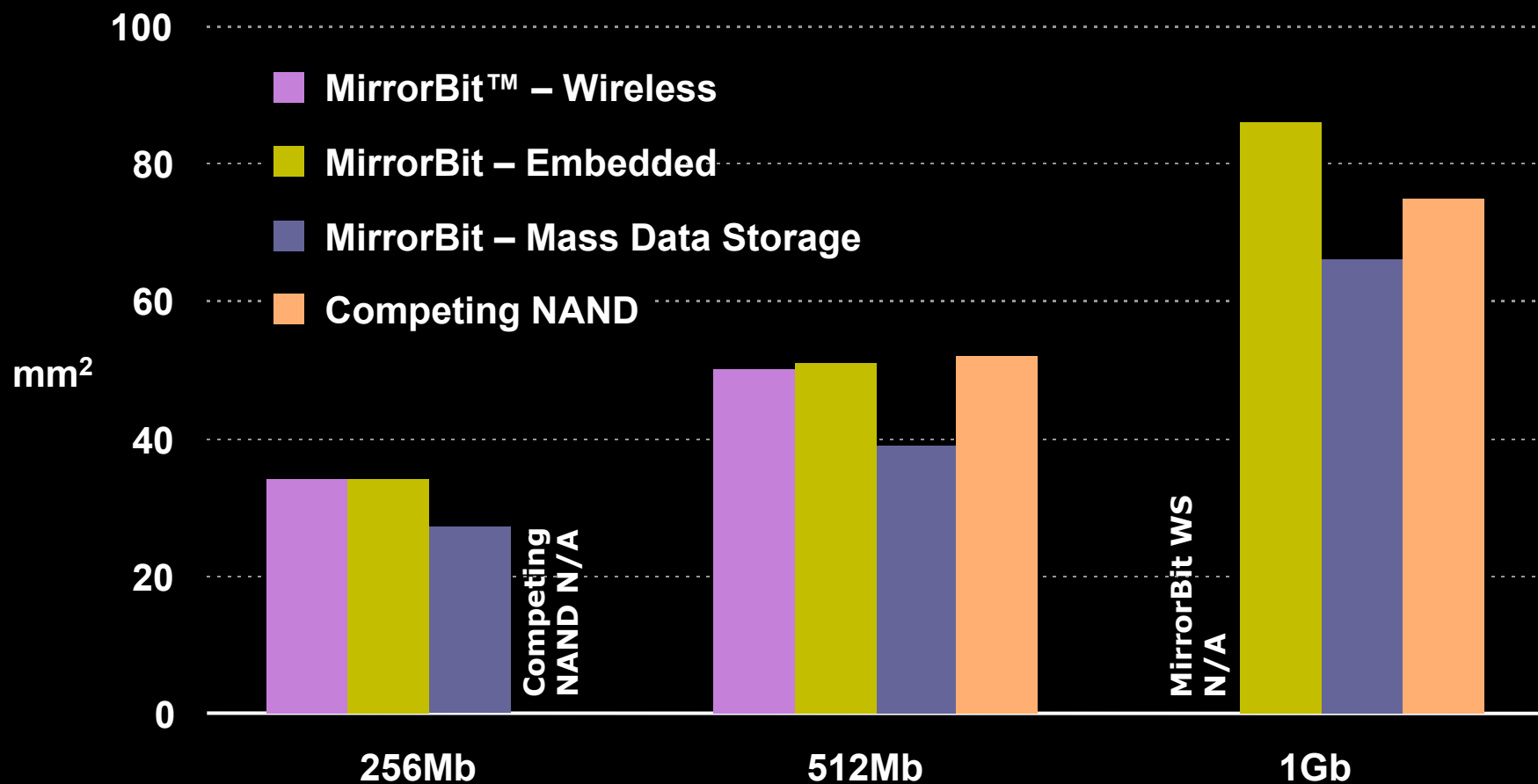
MirrorBit™ Technology

110nm to 65nm

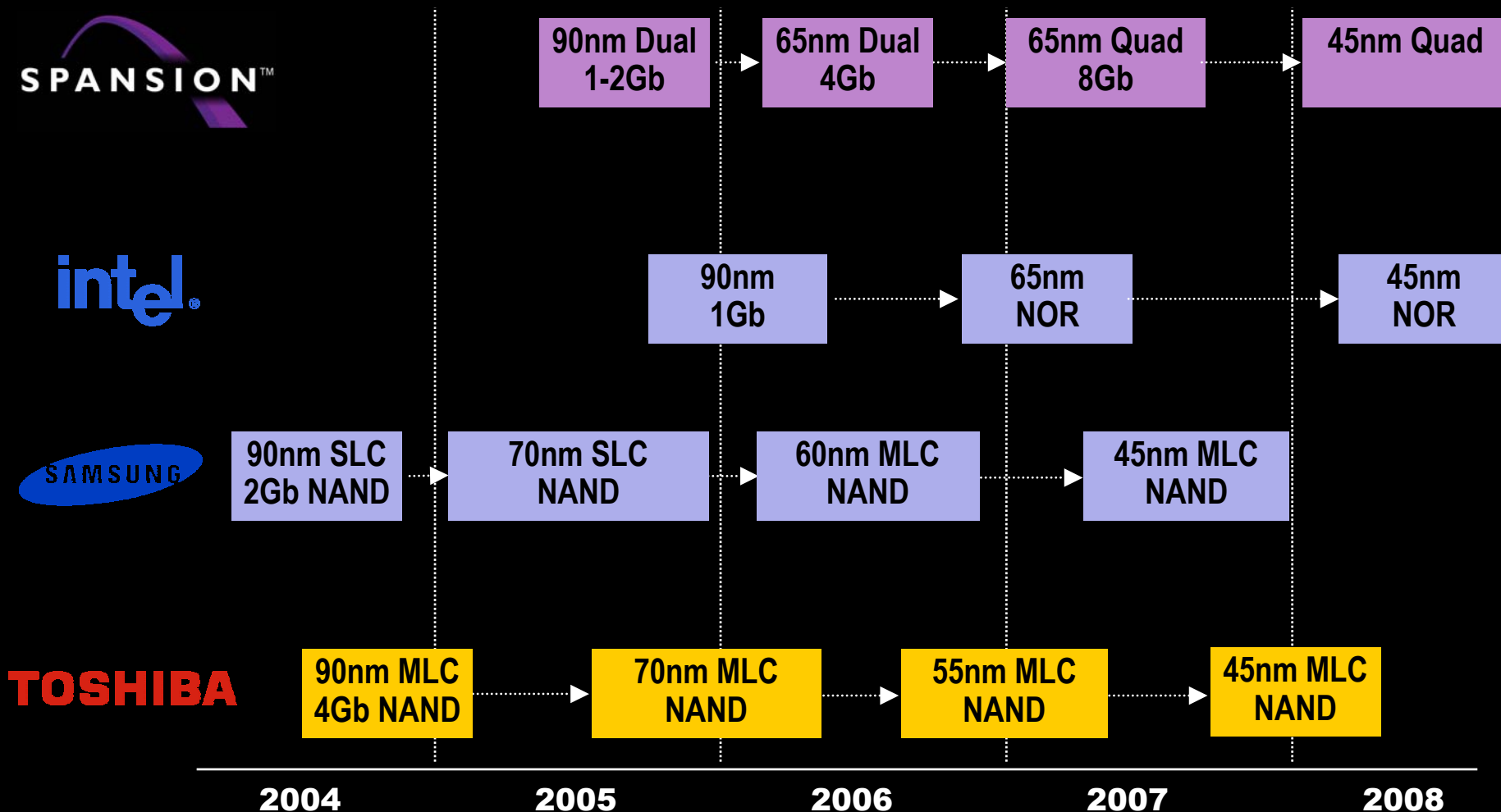
Technology Migration



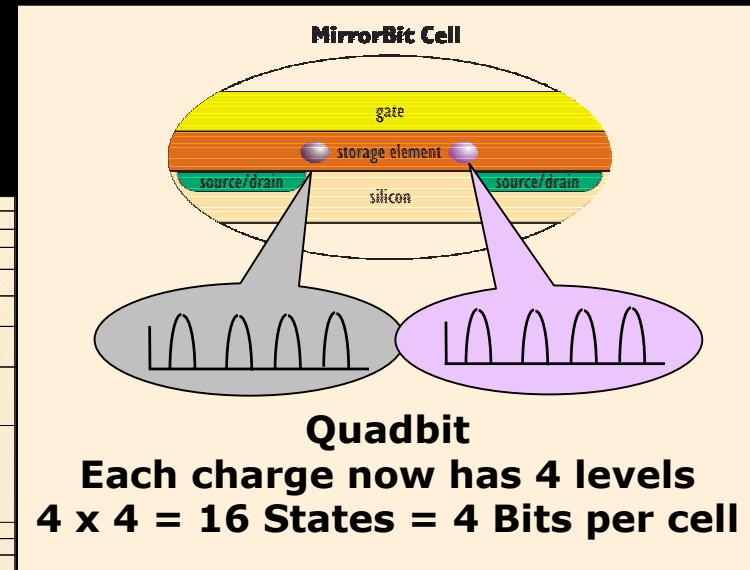
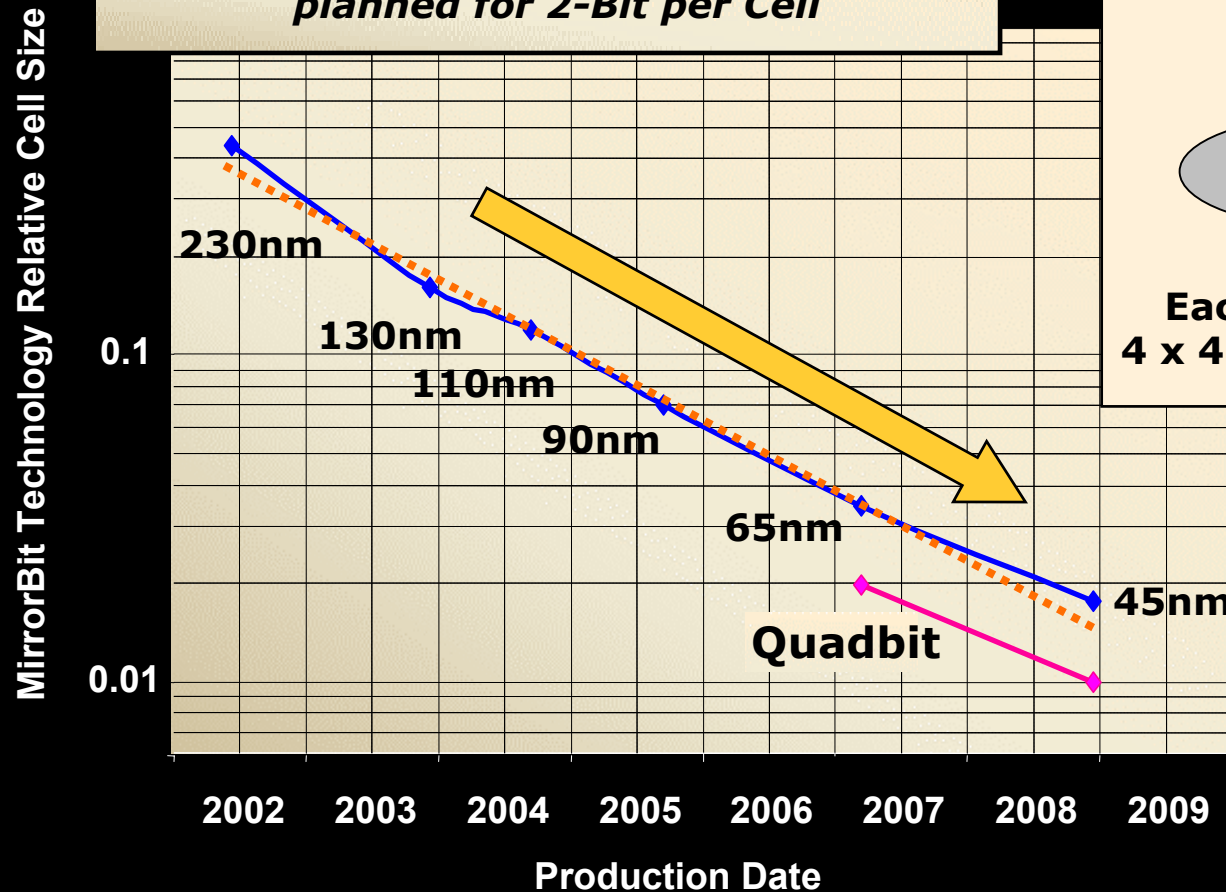
Die Size Comparisons at 90nm



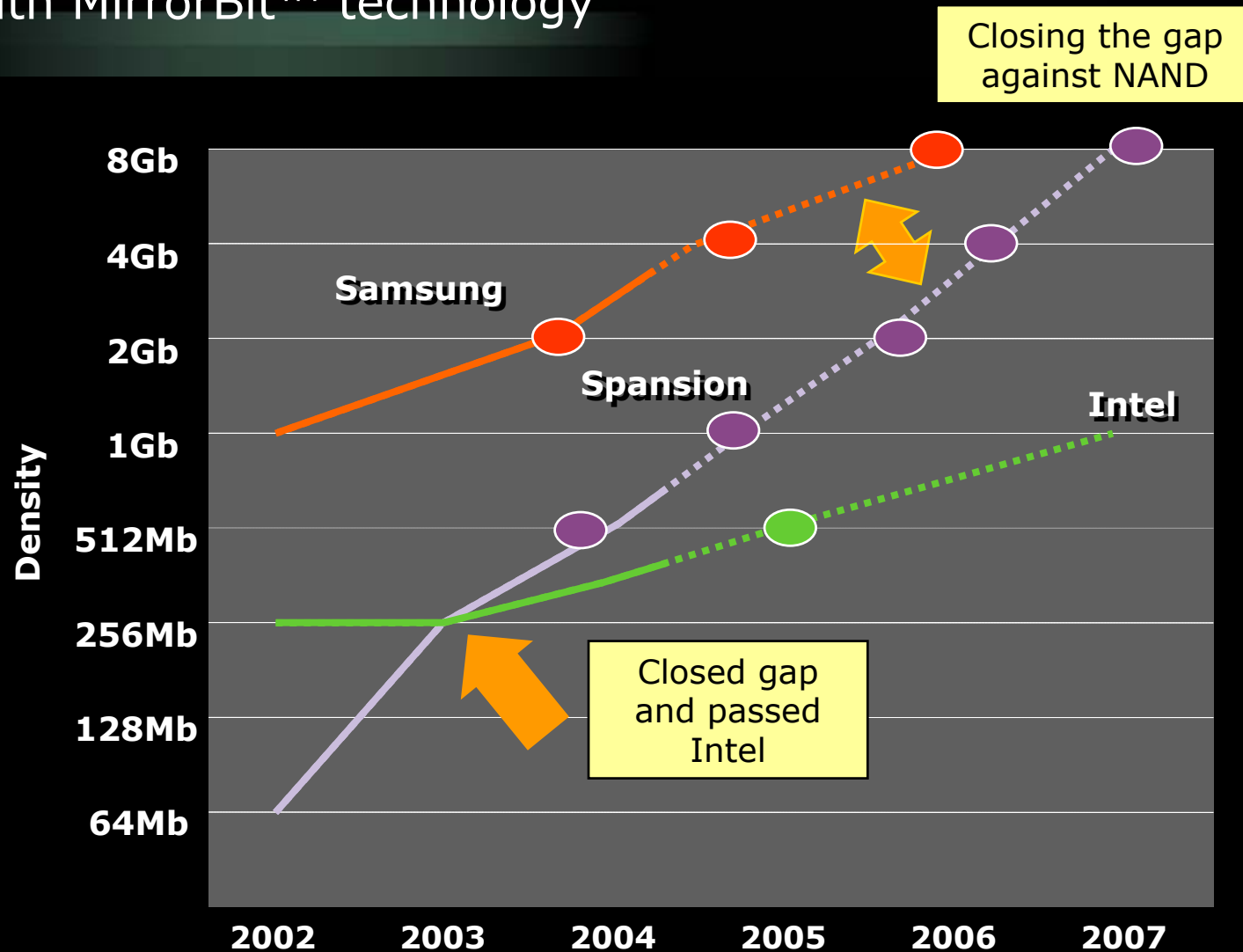
Competitive Technology Roadmaps



MirrorBit™ Technology Relative Cell Size



Closing the Density Gap with MirrorBit™ technology



SP1 300mm Facility - SP1 Aerial View

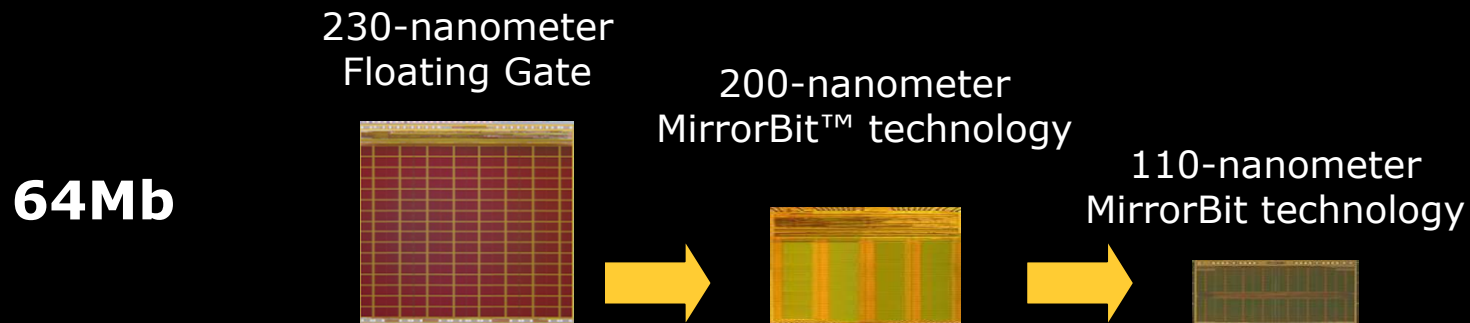


MirrorBit™ Technology: Changing the Rules at Low Density

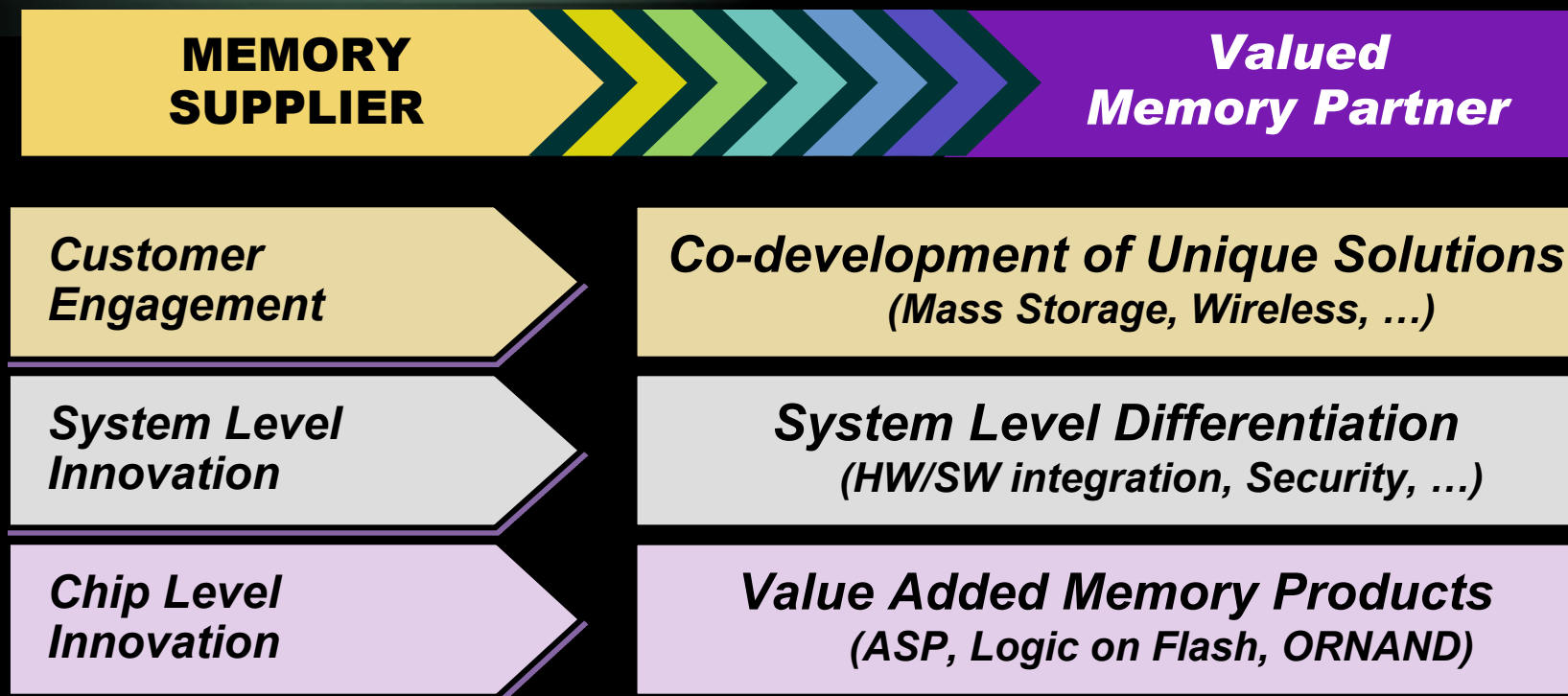


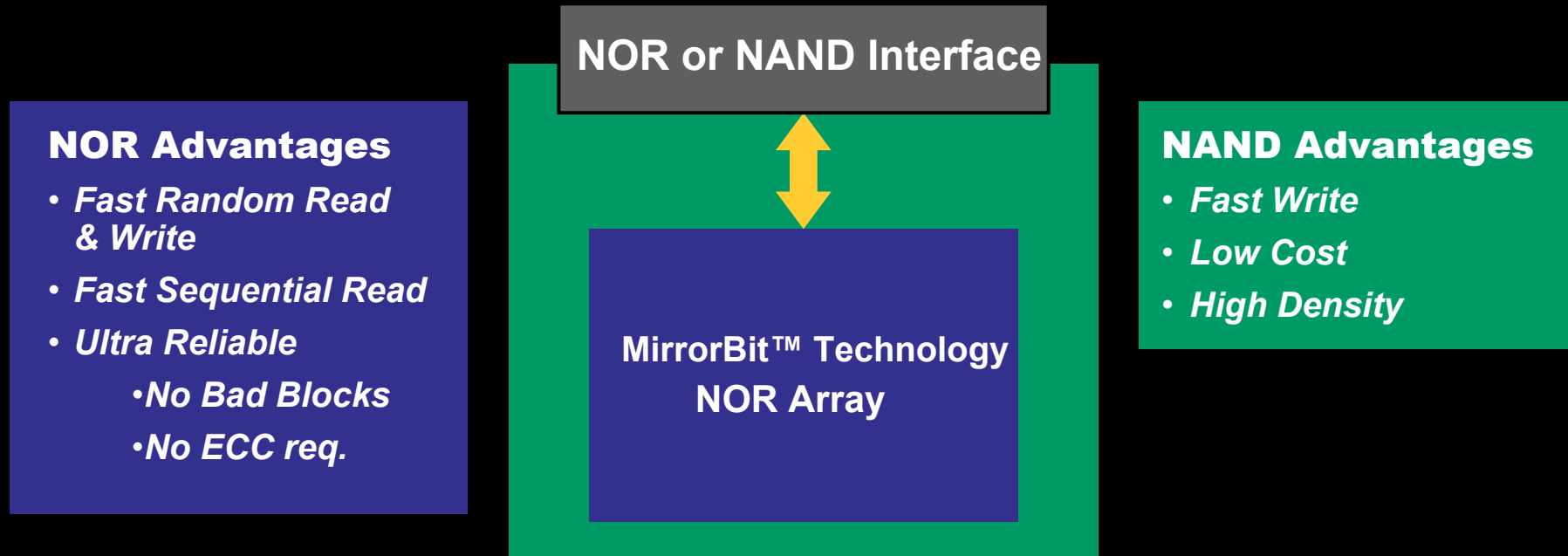
Best Cost Structure Reduction at Low Density (16Mb, 32Mb, 64Mb)

	Conventional FG		MirrorBit™		
	<u>230nm</u>	<u>110nm</u>	<u>230nm</u>	<u>200nm</u>	<u>110nm</u>
Wafer Cost	100%	208%	84%	84%	182%
64Mb NDW	100	363	209	224	504
Die Cost	1.00	0.57	0.40	0.37	0.36



Moving up in the Value Chain





- *Supports Fast Write and Fast Read*
- *High Density and High Reliability*
 - *Integrated Logic*
 - *Lowest Cost*

PISMO™

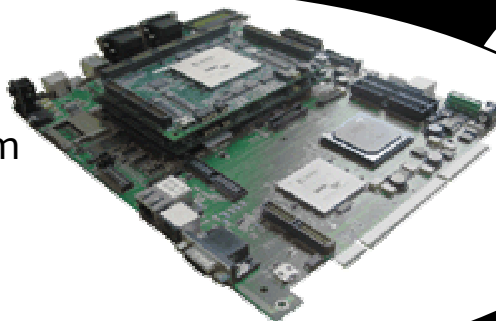
Platform Independent Storage Module



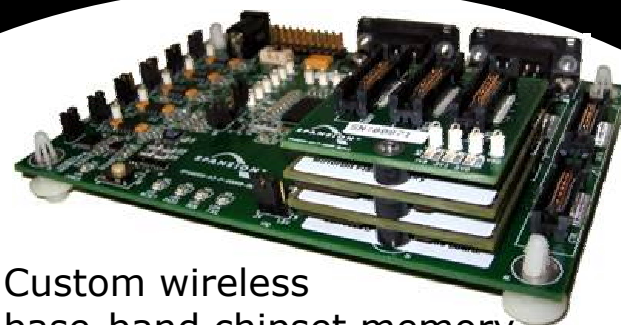
PISMO™ Memory Module(s)
on PCI card

- ***System validation***
- ***Software Driver Development***
- ***Modular memory solution
for development systems***
- ***Open standard (PISMO
Advisory Council)***

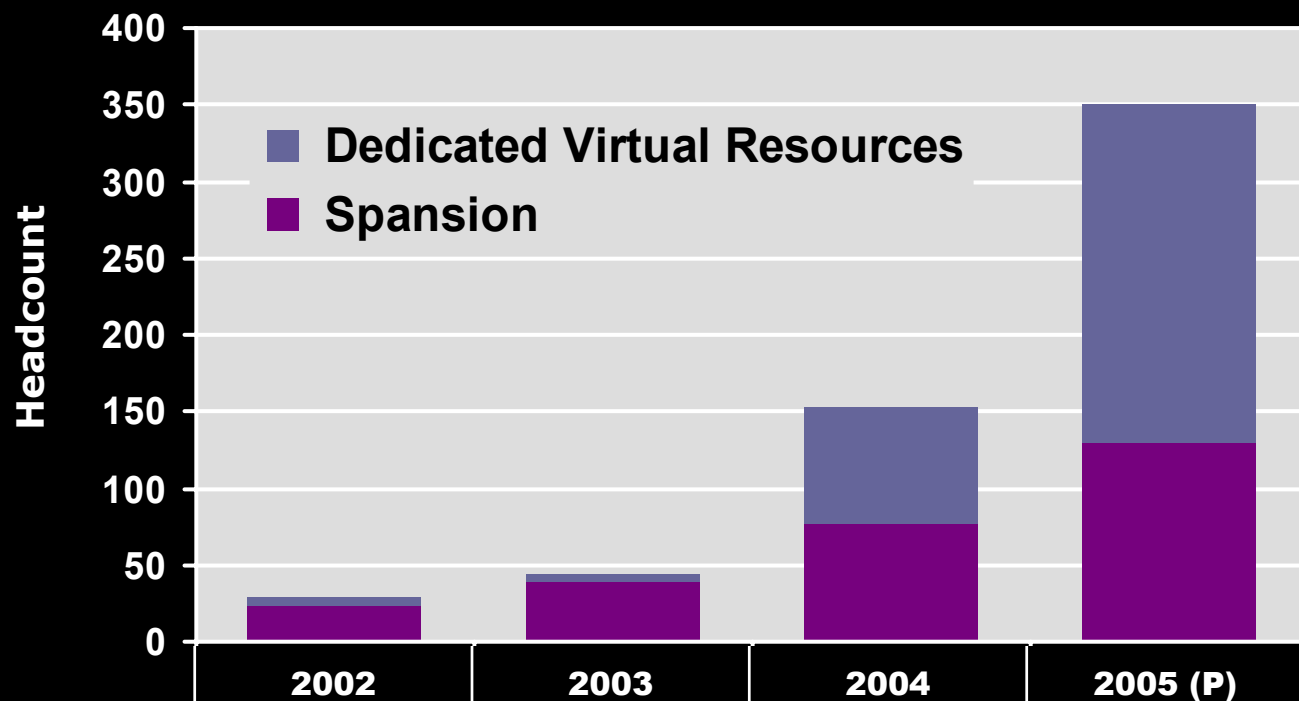
Versatile Platform
Baseboard
for ARM926EJ-S



Custom wireless
base-band chipset memory
validation platform with PISMO

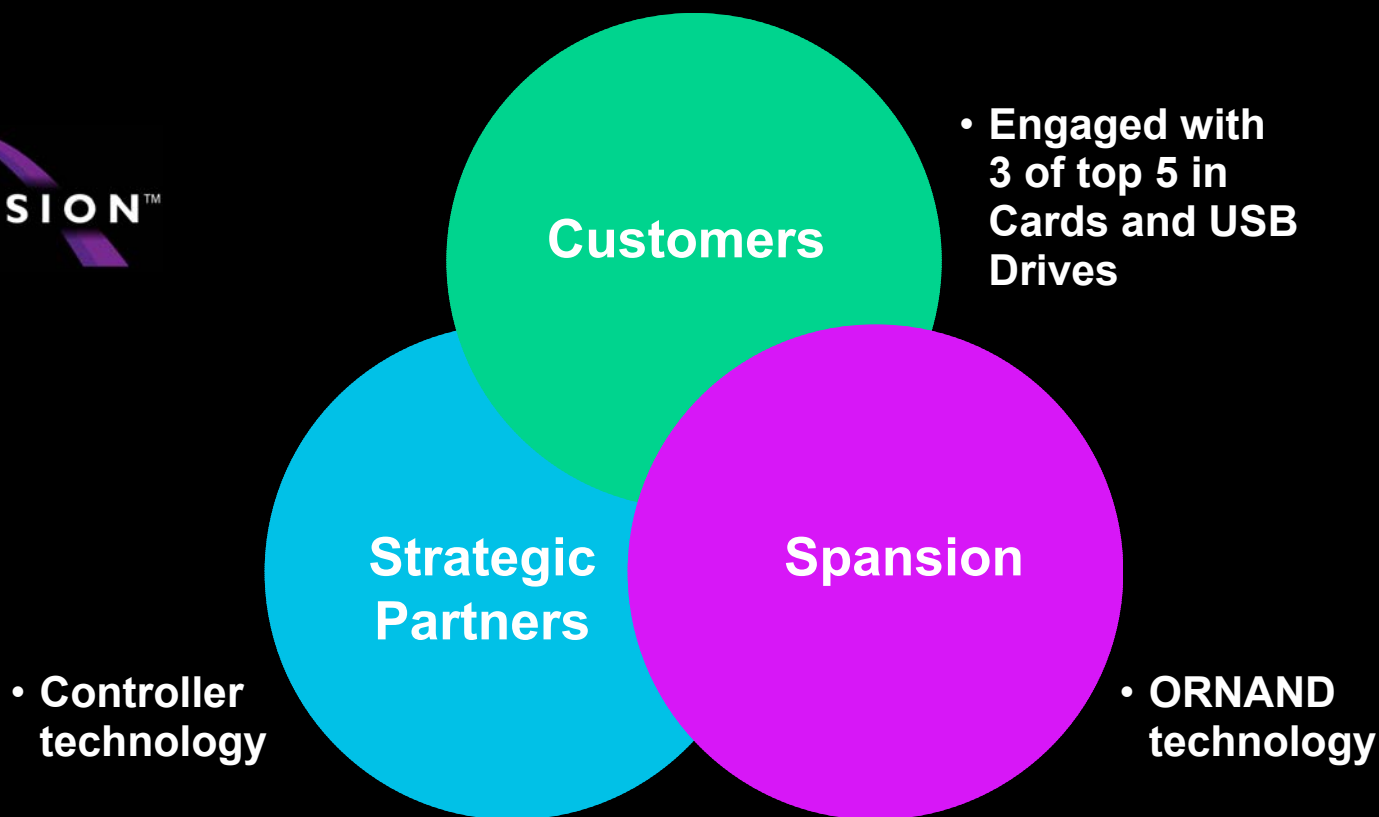


System-Level Resources



	2002	2003	2004	2005 (P)
Dedicated Virtual Resources	5	5	76	221
Spansion	24	39	77	129
TOTAL	29	44	153	350

Joint Development – Customers Specific Solutions



5-step Strategy



Customer Engagement

System Level Innovation

Chip Level Innovation

Innovative Flash Technology

Manufacturing Excellence

Co-development

Memory solutions

Differentiated features

MirrorBit™ Technology

110nm to 65nm



SPANSION™

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